Universal Battery Charger 24Vin 10A max

Battery discharge circuit
Example: 5 ohms off 12V Battery ~30 W

Contact: Engineer: SVN Rev: Number:

Designed for: Sheet:

Sheet Title:

Contact:

Assembly Variant:

File:

Mod. Date:

Engineer:

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With present values: ACIN reaches 2-4V with Vin above 21V.
and above ACIN to go "tight" to

VREF is 3.3V, up to 30mA
VDDP is 6V up to 50mA
VCIM is 200mV / A of ln

With present values: ICOUT alarm goes low with 7.74Ain
and goes high when input current drops below 7.2A
**Universal Battery Charger 24Vin 10A max**

**Design for:**  
Public Release

**Assembly Variant:**  
001

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**Label Table**

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

**PCB Label**

Size: 0.65” x 0.20”

**Assembly Note**

- ZZ1  
  - PCB Assembly Note
  - PCB Assembly Note is for PCB labels only

- ZZ2  
  - PCB Assembly Note
  - These assemblies are ESD sensitive, ESD precautions shall be observed.

- ZZ3  
  - PCB Assembly Note
  - These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

- ZZ4  
  - PCB Assembly Note
  - These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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- Version control disabled

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